LOW CAPACITANCE ESD PROTECTION DIODE ARRAY

Features

- Low Capacitance
- Small Surface Mount Package
- For ESD Protection of High-Speed Data Lines
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

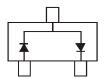
Mechanical Data

- Package: SOT323
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed Over Alloy 42 Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Weight: 0.006 grams (Approximate)

SOT323



Top View



Top View Internal Schematic

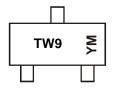
Ordering Information (Note 4)

Part Number	Backago	Packing		
Part Number	Package	Qty.	Carrier	
DESD1P0RFWA-7	SOT323	3,000	Tape & Reel	

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



TW9 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: J = 2022) M = Month (ex: 9 = September)

Date Code Key

Year	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033
Code	J	K	L	М	N	0	Р	R	S	Т	U	V
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec



Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current	lpp	15	Α	8/20µs (Notes 5 & 6)
ESD Protection – Contact Discharge	VESD_Contact	±30	kV	Standard IEC 61000-4-2 (Note 6)
ESD Protection – Air Discharge	VESD_Air	±30	kV	Standard IEC 61000-4-2 (Note 6)

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7)	P _D	200	mW
Thermal Resistance Junction to Ambient Air (Note 7)	Reja	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic (Note 5)	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Working Voltage	VRWM	_	_	70	V	_
Reverse Current	I _{RM}	_	_	100	nA	$V_{RM} = 70V$
Forward Clamping Voltage (Note 6)	VFC	_	2	6	V	I _{PP} = 3A, per IEC 61000-4-5 (Note 8)
Tomara clamping voltage (Note of	VFC	_	4	8		IPP = 10A, per IEC 61000-4-5 (Note 8)
Canacitanas	C-	_	1	1.5	pF	V _R = 0V, f = 1MHz (Note 9)
Capacitance	Ст	_	1.7	2.5	þΕ	$V_R = 0V$, $f = 1MHz$ (Note 10)

Notes:

- 5. Diodes short duration pulse test used to minimize self-heating effect.
- 6. Anti-parallel connection.
- 7. Device mounted on FR-4 PCB with minimum recommended pad layout.
- 8. Clamping voltage value is based on an 8x20µs peak pulse current (I_{PP}) waveform.
 9. Total capacitance line to ground (per diode).
 10. Total capacitance line to ground (anti-parallel connection).



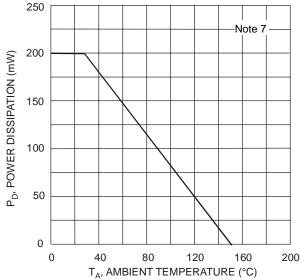
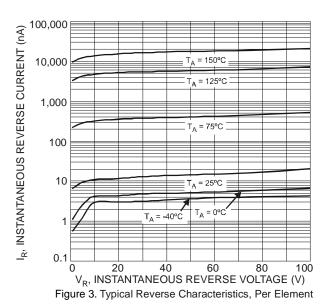


Figure 1. Power Derating Curve, Total Package



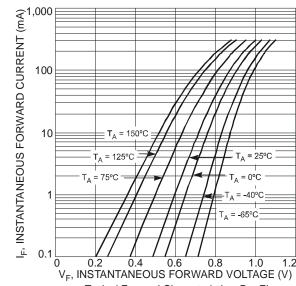


Figure 2. Typical Forward Characteristics, Per Element

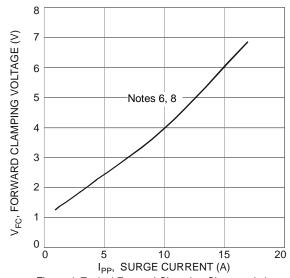


Figure 4. Typical Forward Clamping Characteristics

Notes:

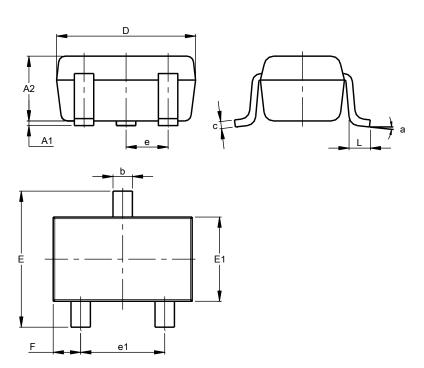
- 6. Anti-parallel connection.
- 7. Device mounted on FR-4 PCB with minimum recommended pad layout.
- 8. Clamping voltage value is based on an 8×20µs peak pulse current (IPP) waveform.



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT323



SOT323							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.90	1.00	0.95				
b	0.25	0.40	0.30				
С	0.10	0.18	0.11				
D	1.80	2.20	2.15				
Е	2.00	2.20	2.10				
E1	1.15	1.35	1.30				
е	0.650 BSC						
e1	1.20	1.40	1.30				
F	0.375	0.475	0.425				
L	0.25	0.40	0.30				
а	0°	8°					
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

Y1 G +

SOT323

Dimensions	Value (in mm)
С	0.650
G	1.300
Х	0.470
Υ	0.600
Y1	2.500



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